

Product Change Notification / NTDO-04BHBR022

Date:

17-Nov-2021

Product Category:

Closed Fan Controllers, Current And Power Measurement ICs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4782 Initial Notice: Qualification of MTAI as an additional assembly site for SMSC selected EMC1701, EMC1702, EMC2103 and EMC2303 device families available in 12L QFN (4x4x0.9mm) package assembled at ASE.

Affected CPNs:

NTDO-04BHBR022_Affected_CPN_11172021.pdf NTDO-04BHBR022_Affected_CPN_11172021.csv

Notification Text:

PCN Status:Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of MTAI as an additional assembly site for SMSC selected EMC1701, EMC1702, EMC2103 and EMC2303 device families available in 12L QFN (4x4x0.9mm) package assembled at ASE.

Pre and Post Change Summary:

	Pre Change	Post Change		
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Microchip Technology Thailand (HQ) MTAI	
Wire Material	Au / PdCu	Au / PdCu	Au	
Die Attach Material	EN-4900F	EN-4900F	QMI-519	
Molding Compound Material	G631H	G631H	G700LTD	
Lead-Frame Material	A194	A194	A194	
Lead-Frame Paddle Size	91 x 91 mm	91 x 91 mm	91 x 91 mm	
Lead-Frame Lead-lock	No	Yes	Yes	
DAP Surface Prep	Ag ring plating	Ag ring plating	Ag ring plating	

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date:November 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	November 2021				
Workweek	4	4	4	4	4
Workwook	5	6	7	8	9
Initial PCN Issue			v		
Date			Х		
Qual Report					v
Availability					Х
Final PCN Issue					v
Date					Х

Method to Identify Change:Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: November 17, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_NTDO-04BHBR022_Pre_and_Post_Change_Summary.pdf PCN_NTDO-04BHBR022_Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. NTDO-04BHBR022 - CCB 4782 Initial Notice: Qualification of MTAI as an additional assembly site for SMSC selected EMC1701, EMC1702, EMC2103 and EMC2303 device families available in 12L QFN (4x4x0.9mm) package assembled at ASE.

Affected Catalog Part Numbers (CPN)

EMC1701-1-KP-TR EMC1702-1-KP-TR EMC2103-1-KP-TR EMC2103-1-KP-TR EMC2303-1-KP-TR